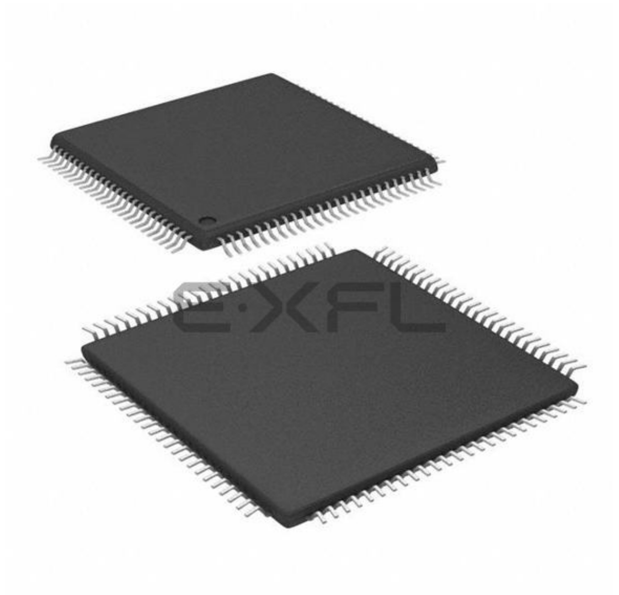


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	85
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 32x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24hj128gp210-i-pt

2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to 4 MHz < F_{IN} < 8 MHz to comply with device PLL start-up conditions. This means that if the external oscillator frequency is outside this range, the application must start-up in the FRC mode first. The default PLL settings after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can initialize the PLL SFRs, CLKDIV and PLLDBF to a suitable value, and then perform a clock switch to the Oscillator + PLL clock source. Note that clock switching must be enabled in the device Configuration word.

2.8 Configuration of Analog and Digital Pins During ICSP Operations

If MPLAB ICD 2, ICD 3 or REAL ICE is selected as a debugger, it automatically initializes all of the A/D input pins (ANx) as “digital” pins, by setting all bits in the AD1PCFGL register.

The bits in this register that correspond to the A/D pins that are initialized by MPLAB ICD 2, ICD 3, or REAL ICE, must not be cleared by the user application firmware; otherwise, communication errors will result between the debugger and the device.

If your application needs to use certain A/D pins as analog input pins during the debug session, the user application must clear the corresponding bits in the AD1PCFGL register during initialization of the ADC module.

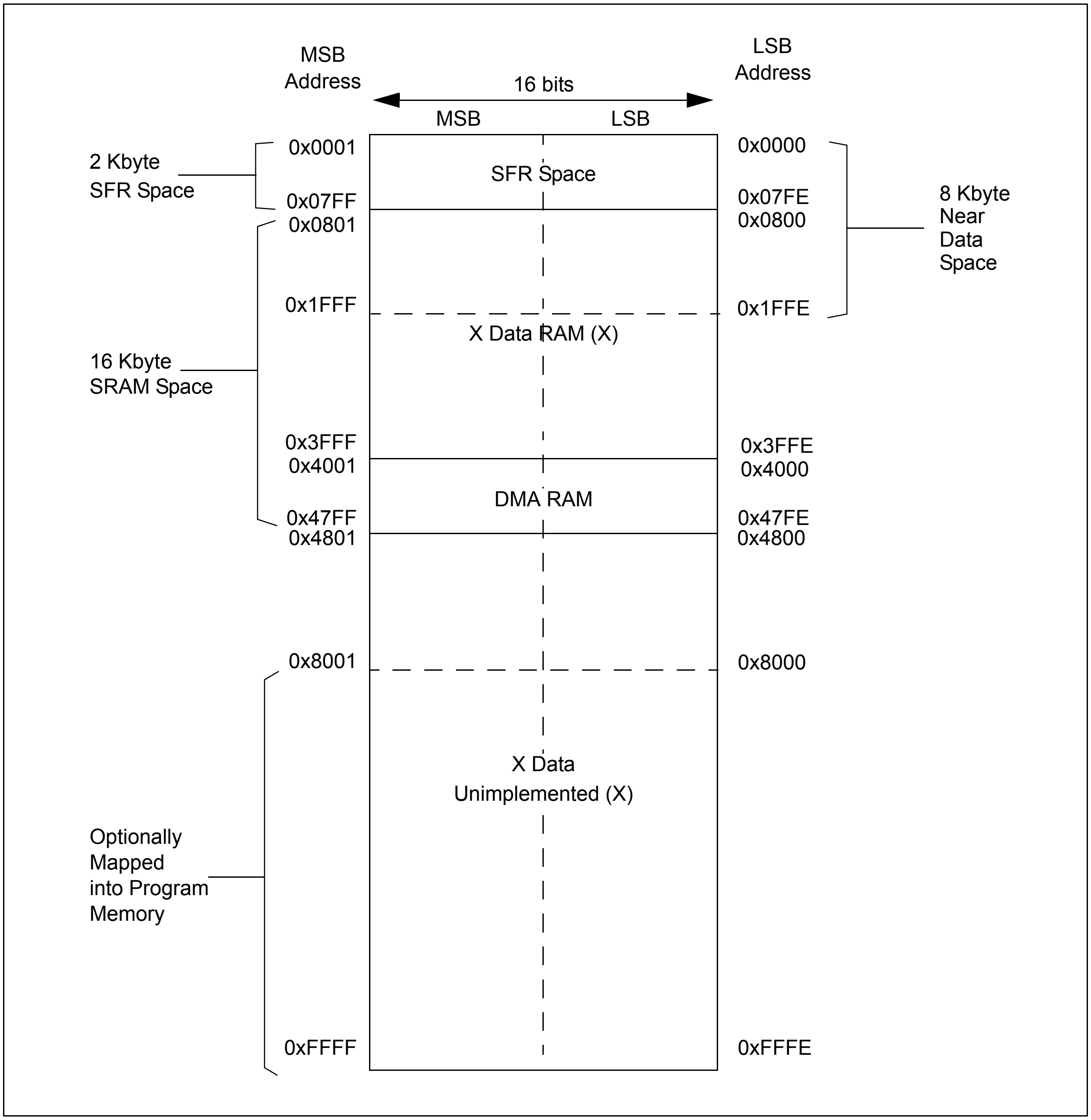
When MPLAB ICD 2, ICD 3 or REAL ICE is used as a programmer, the user application firmware must correctly configure the AD1PCFGL register. Automatic initialization of this register is only done during debugger operation. Failure to correctly configure the register(s) will result in all A/D pins being recognized as analog input pins, resulting in the port value being read as a logic ‘0’, which may affect user application functionality.

2.9 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic-low state.

Alternatively, connect a 1k to 10k resistor to V_{SS} on unused pins and drive the output to logic low.

FIGURE 4-4: DATA MEMORY MAP FOR PIC24HJXXXGPX06/X08/X10 DEVICES WITH 16 KBS RAM



4.2.5 DMA RAM

Every PIC24HJXXXGPX06/X08/X10 device contains 2 Kbytes of dual ported DMA RAM located at the end of data space. Memory locations in the DMA RAM space are accessible simultaneously by the CPU and the DMA controller module. DMA RAM is utilized by the DMA controller to store data to be transferred to various peripherals using DMA, as well as data transferred from various peripherals using DMA. The DMA RAM can be accessed by the DMA controller without having to steal cycles from the CPU.

When the CPU and the DMA controller attempt to concurrently write to the same DMA RAM location, the hardware ensures that the CPU is given precedence in accessing the DMA RAM location. Therefore, the DMA RAM provides a reliable means of transferring DMA data without ever having to stall the CPU.

Note:	DMA RAM can be used for general purpose data storage if the DMA function is not required in an application.

TABLE 4-23: ECAN2 REGISTER MAP WHEN C2CTRL1.WIN = 1 FOR PIC24HJ256GP610 DEVICES ONLY (CONTINUED)

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
C2RXF11EID	056E	EID<15:8>								EID<7:0>								xxxx
C2RXF12SID	0570	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF12EID	0572	EID<15:8>								EID<7:0>								xxxx
C2RXF13SID	0574	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF13EID	0576	EID<15:8>								EID<7:0>								xxxx
C2RXF14SID	0578	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF14EID	057A	EID<15:8>								EID<7:0>								xxxx
C2RXF15SID	057C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C2RXF15EID	057E	EID<15:8>								EID<7:0>								xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal for PinHigh devices.

5.0 FLASH PROGRAM MEMORY

Note:	This data sheet summarizes the features of the PIC24HJXXXGPX06/X08/X10 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"PIC24H Family Reference Manual"*, **Section 5. "Flash Programming"** (DS70228), which is available from the Microchip website (www.microchip.com).

The PIC24HJXXXGPX06/X08/X10 devices contain internal Flash program memory for storing and executing application code. The memory is readable, writable and erasable during normal operation over the entire V_{DD} range.

Flash memory can be programmed in two ways:

1. In-Circuit Serial Programming™ (ICSP™) programming capability
2. Run-Time Self-Programming (RTSP)

ICSP programming capability allows a PIC24HJXXXGPX06/X08/X10 device to be serially programmed while in the end application circuit. This is simply done with two lines for programming clock and programming data (one of the alternate programming pin pairs: PGECx/PGEDx, and three other lines for power (V_{DD}), ground (V_{SS}) and Master Clear ($\overline{MCLR}$). This allows customers to manufacture boards with unprogrammed devices and then program the digital signal controller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

RTSP is accomplished using `TBLRD` (table read) and `TBLWT` (table write) instructions. With RTSP, the user can write program memory data either in blocks or 'rows' of 64 instructions (192 bytes) at a time, or single instructions and erase program memory in blocks or 'pages' of 512 instructions (1536 bytes) at a time.

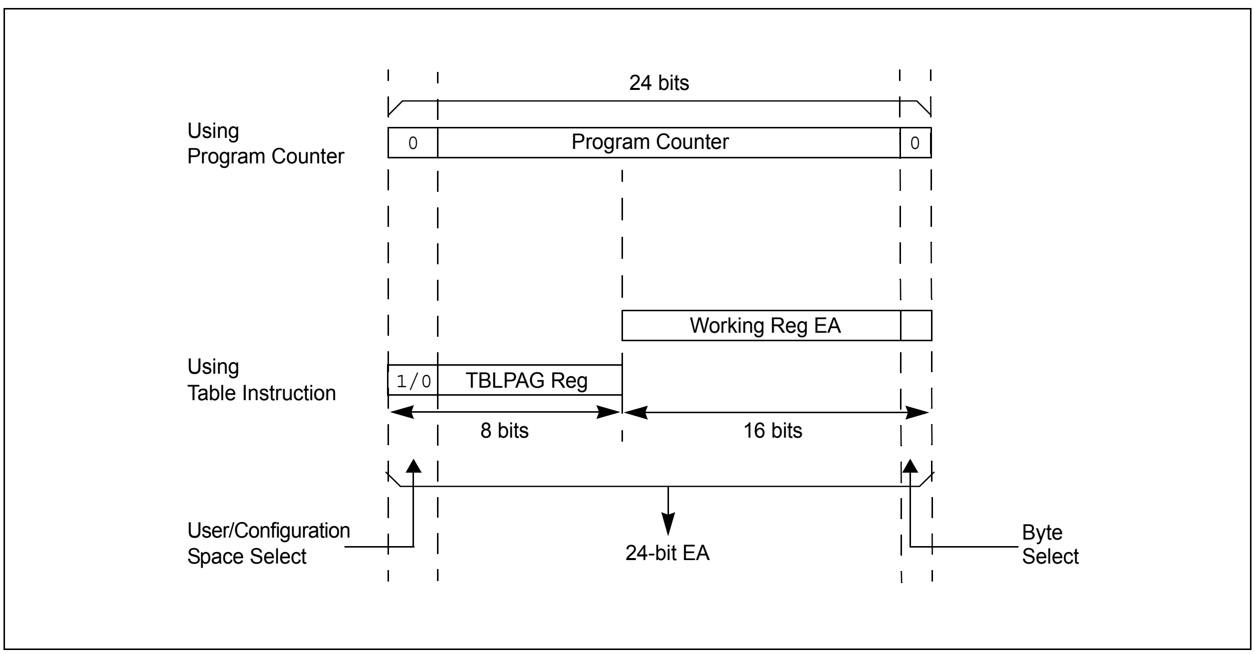
5.1 Table Instructions and Flash Programming

Regardless of the method used, all programming of Flash memory is done with the table read and table write instructions. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using bits<7:0> of the TBLPAG register and the Effective Address (EA) from a W register specified in the table instruction, as shown in Figure 5-1.

The `TBLRDL` and the `TBLWTL` instructions are used to read or write to bits<15:0> of program memory. `TBLRDL` and `TBLWTL` can access program memory in both Word and Byte modes.

The `TBLRDH` and `TBLWTH` instructions are used to read or write to bits<23:16> of program memory. `TBLRDH` and `TBLWTH` can also access program memory in Word or Byte mode.

FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS



5.2 RTSP Operation

The PIC24HJXXXGPX06/X08/X10 Flash program memory array is organized into rows of 64 instructions or 192 bytes. RTSP allows the user to erase a page of memory, which consists of eight rows (512 instructions) at a time, and to program one row or one word at a time. Table 24-12 displays typical erase and programming times. The 8-row erase pages and single row write rows are edge-aligned, from the beginning of program memory, on boundaries of 1536 bytes and 192 bytes, respectively.

The program memory implements holding buffers that can contain 64 instructions of programming data. Prior to the actual programming operation, the write data must be loaded into the buffers in sequential order. The instruction words loaded must always be from a group of 64 boundary.

The basic sequence for RTSP programming is to set up a Table Pointer, then do a series of `TBLWT` instructions to load the buffers. Programming is performed by setting the control bits in the NVMCON register. A total of 64 `TBLWTL` and `TBLWTH` instructions are required to load the instructions.

All of the table write operations are single-word writes (two instruction cycles) because only the buffers are written. A programming cycle is required for programming each row.

5.3 Programming Operations

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. The processor stalls (waits) until the programming operation is finished.

The programming time depends on the FRC accuracy (see Table 24-19) and the value of the FRC Oscillator Tuning register (see Register 9-4). Use the following formula to calculate the minimum and maximum values for the Row Write Time, Page Erase Time and Word Write Cycle Time parameters (see Table 24-12).

EQUATION 5-1: PROGRAMMING TIME

$$\frac{T}{7.37\ MHz \times (FRC\ Accuracy)\% \times (FRC\ Tuning)\%}$$

For example, if the device is operating at +85°C, the FRC accuracy will be ±2%. If the TUN<5:0> bits (see Register 9-4) are set to `'b111111`, the Minimum Row Write Time is:

$$T_{RW} = \frac{11064\ Cycles}{7.37\ MHz \times (1 + 0.02) \times (1 - 0.00375)} = 1.48ms$$

and, the Maximum Row Write Time is:

$$T_{RW} = \frac{11064\ Cycles}{7.37\ MHz \times (1 - 0.02) \times (1 - 0.00375)} = 1.54ms$$

Setting the WR bit (NVMCON<15>) starts the operation, and the WR bit is automatically cleared when the operation is finished.

5.4 Control Registers

There are two SFRs used to read and write the program Flash memory: NVMCON and NVMKEY.

The NVMCON register (Register 5-1) controls which blocks are to be erased, which memory type is to be programmed and the start of the programming cycle.

NVMKEY is a write-only register that is used for write protection. To start a programming or erase sequence, the user must consecutively write 0x55 and 0xAA to the NVMKEY register. Refer to **Section 5.3 "Programming Operations"** for further details.

NOTES:

TABLE 6-3: RESET DELAY TIMES FOR VARIOUS DEVICE RESETS

Reset Type	Clock Source	$\overline{\text{SYSRST}}$ Delay	System Clock Delay	FSCM Delay	Notes
POR	EC, FRC, LPRC	$T_{POR} + T_{STARTUP} + T_{RST}$	—	—	**1, 2, 3**
	ECPLL, FRCPLL	$T_{POR} + T_{STARTUP} + T_{RST}$	T_{LOCK}	T_{FSCM}	**1, 2, 3, 5, 6**
	XT, HS, SOSC	$T_{POR} + T_{STARTUP} + T_{RST}$	T_{OST}	T_{FSCM}	**1, 2, 3, 4, 6**
	XTPLL, HSPLL	$T_{POR} + T_{STARTUP} + T_{RST}$	$T_{OST} + T_{LOCK}$	T_{FSCM}	**1, 2, 3, 4, 5, 6**
$\overline{\text{MCLR}}$	Any Clock	T_{RST}	—	—	**3**
WDT	Any Clock	T_{RST}	—	—	**3**
Software	Any clock	T_{RST}	—	—	**3**
Illegal Opcode	Any Clock	T_{RST}	—	—	**3**
Uninitialized W	Any Clock	T_{RST}	—	—	**3**
Trap Conflict	Any Clock	T_{RST}	—	—	**3**

Note 1: T_{POR} = Power-on Reset delay (10 µs nominal).
2: $T_{STARTUP}$ = Conditional POR delay of 20 µs nominal (if on-chip regulator is enabled) or 64 ms nominal Power-up Timer delay (if regulator is disabled). $T_{STARTUP}$ is also applied to all returns from powered-down states, including waking from Sleep mode, only if the regulator is enabled.
3: T_{RST} = Internal state Reset time (20 µs nominal).
4: T_{OST} = Oscillator Start-up Timer. A 10-bit counter counts 1024 oscillator periods before releasing the oscillator clock to the system.
5: T_{LOCK} = PLL lock time (20 µs nominal).
6: T_{FSCM} = Fail-Safe Clock Monitor delay (100 µs nominal).

6.2.1 POR AND LONG OSCILLATOR START-UP TIMES

The oscillator start-up circuitry and its associated delay timers are not linked to the device Reset delays that occur at power-up. Some crystal circuits (especially low-frequency crystals) have a relatively long start-up time. Therefore, one or more of the following conditions is possible after the Reset signal is released:

- The oscillator circuit has not begun to oscillate.
- The Oscillator Start-up Timer has not expired (if a crystal oscillator is used).
- The PLL has not achieved a lock (if PLL is used).

The device will not begin to execute code until a valid clock source has been released to the system. Therefore, the oscillator and PLL start-up delays must be considered when the Reset delay time must be known.

6.2.2 FAIL-SAFE CLOCK MONITOR (FSCM) AND DEVICE RESETS

If the FSCM is enabled, it begins to monitor the system clock source when the Reset signal is released. If a valid clock source is not available at this time, the device automatically switches to the FRC oscillator and the user can switch to the desired crystal oscillator in the Trap Service Routine.

6.2.2.1 FSCM Delay for Crystal and PLL Clock Sources

When the system clock source is provided by a crystal oscillator and/or the PLL, a small delay, T_{FSCM}, is automatically inserted after the POR and PWRT delay times. The FSCM does not begin to monitor the system clock source until this delay expires. The FSCM delay time is nominally 500 µs and provides additional time for the oscillator and/or PLL to stabilize. In most cases, the FSCM delay prevents an oscillator failure trap at a device Reset when the PWRT is disabled.

6.3 Special Function Register Reset States

Most of the Special Function Registers (SFRs) associated with the CPU and peripherals are reset to a particular value at a device Reset. The SFRs are grouped by their peripheral or CPU function and their Reset values are specified in each section of this manual.

The Reset value for each SFR does not depend on the type of Reset, with the exception of two registers. The Reset value for the Reset Control register, RCON, depends on the type of device Reset. The Reset value for the Oscillator Control register, OSCCON, depends on the type of Reset and the programmed values of the oscillator Configuration bits in the FOSC Configuration register.

REGISTER 8-1: DMAxCON: DMA CHANNEL x CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0
CHEN	SIZE	DIR	HALF	NULLW	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0
—	—	AMODE<1:0>		—	—	MODE<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CHEN:** Channel Enable bit
1 = Channel enabled
0 = Channel disabled

bit 14 **SIZE:** Data Transfer Size bit
1 = Byte
0 = Word

bit 13 **DIR:** Transfer Direction bit (source/destination bus select)
1 = Read from DMA RAM address, write to peripheral address
0 = Read from peripheral address, write to DMA RAM address

bit 12 **HALF:** Early Block Transfer Complete Interrupt Select bit
1 = Initiate block transfer complete interrupt when half of the data has been moved
0 = Initiate block transfer complete interrupt when all of the data has been moved

bit 11 **NULLW:** Null Data Peripheral Write Mode Select bit
1 = Null data write to peripheral in addition to DMA RAM write (DIR bit must also be clear)
0 = Normal operation

bit 10-6 **Unimplemented:** Read as ‘0’

bit 5-4 **AMODE<1:0>:** DMA Channel Operating Mode Select bits
11 = Reserved
10 = Peripheral Indirect Addressing mode
01 = Register Indirect without Post-Increment mode
00 = Register Indirect with Post-Increment mode

bit 3-2 **Unimplemented:** Read as ‘0’

bit 1-0 **MODE<1:0>:** DMA Channel Operating Mode Select bits
11 = One-Shot, Ping-Pong modes enabled (one block transfer from/to each DMA RAM buffer)
10 = Continuous, Ping-Pong modes enabled
01 = One-Shot, Ping-Pong modes disabled
00 = Continuous, Ping-Pong modes disabled

9.0 OSCILLATOR CONFIGURATION

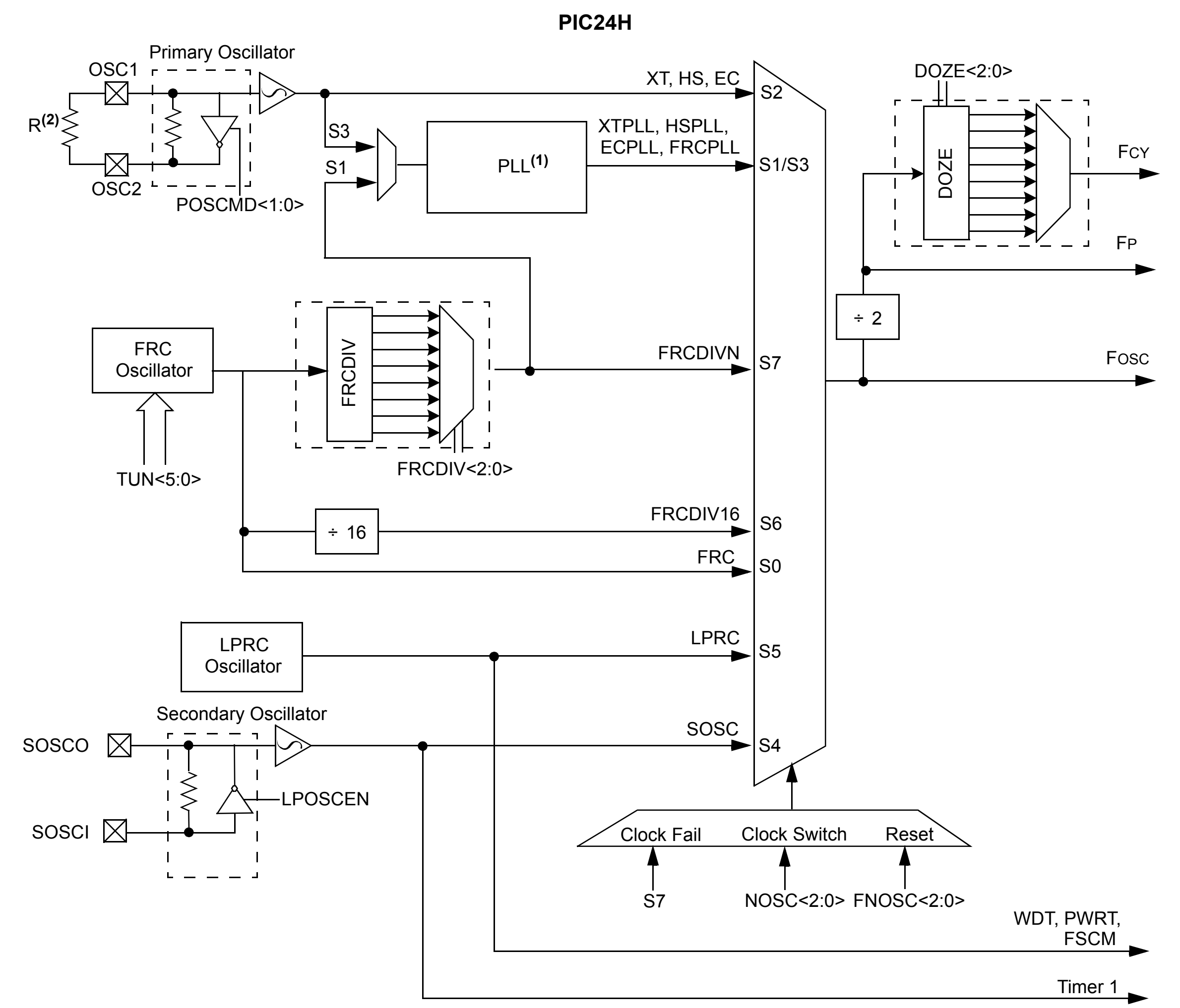
Note:	This data sheet summarizes the features of the PIC24HJXXXGPX06/X08/X10 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"PIC24H Family Reference Manual"*, **Section 7. "Oscillator"** (DS70227), which is available from the Microchip website (www.microchip.com).

The PIC24HJXXXGPX06/X08/X10 oscillator system provides:

- Various external and internal oscillator options as clock sources
- An on-chip PLL to scale the internal operating frequency to the required system clock frequency
- The internal FRC oscillator can also be used with the PLL, thereby allowing full-speed operation without any external clock generation hardware
- Clock switching between various clock sources
- Programmable clock postscaler for system power savings
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and takes fail-safe measures
- A Clock Control register (OSCCON)
- Nonvolatile Configuration bits for main oscillator selection.

A simplified diagram of the oscillator system is shown in Figure 9-1.

FIGURE 9-1: PIC24HJXXXGPX06/X08/X10 OSCILLATOR SYSTEM DIAGRAM



Note 1: See Figure 9-2 for PLL details.

2: If the Oscillator is used with XT or HS modes, an extended parallel resistor with the value of 1 MΩ must be connected.

10.0 POWER-SAVING FEATURES

Note:	This data sheet summarizes the features of the PIC24HJXXXGPX06/X08/X10 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"PIC24H Family Reference Manual"*, **Section 9. "Watchdog Timer and Power-Saving Modes"** (DS70236), which is available from the Microchip website (www.microchip.com).

The PIC24HJXXXGPX06/X08/X10 devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. PIC24HJXXXGPX06/X08/X10 devices can manage power consumption in four different ways:

- Clock frequency
- Instruction-based Sleep and Idle modes
- Software-controlled Doze mode
- Selective peripheral control in software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

PIC24HJXXXGPX06/X08/X10 devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSC bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.2 Instruction-Based Power-Saving Modes

PIC24HJXXXGPX06/X08/X10 devices have two special power-saving modes that are entered through the execution of a special `PWRSAV` instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembly syntax of the `PWRSAV` instruction is shown in Example 10-1.

Note:	SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

10.2.1 SLEEP MODE

Sleep mode has these features:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption is reduced to a minimum, provided that no I/O pin is sourcing current.
- The Fail-Safe Clock Monitor does not operate during Sleep mode since the system clock source is disabled.
- The LPRC clock continues to run in Sleep mode if the WDT is enabled.
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode.
- Some device features or peripherals may continue to operate in Sleep mode. This includes items such as the input change notification on the I/O ports, or peripherals that use an external clock input. Any peripheral that requires the system clock source for its operation is disabled in Sleep mode.

The device will wake-up from Sleep mode on any of these events:

- Any interrupt source that is individually enabled.
- Any form of device Reset.
- A WDT time-out.

On wake-up from Sleep, the processor restarts with the same clock source that was active when Sleep mode was entered.

EXAMPLE 10-1: `PWRSAV` INSTRUCTION SYNTAX

```
PWRSAV  #SLEEP_MODE    ; Put the device into SLEEP mode
PWRSAV  #IDLE_MODE     ; Put the device into IDLE mode
```


REGISTER 16-1: SPIxSTAT: SPIx STATUS AND CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
SPIEN	—	SPISIDL	—	—	—	—	—
bit 15							bit 8

U-0	R/C-0	U-0	U-0	U-0	U-0	R-0	R-0
—	SPIROV	—	—	—	—	SPITBF	SPIRBF
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **SPIEN:** SPIx Enable bit
1 = Enables module and configures SCKx, SDOx, SDIx and $\overline{\text{SSx}}$ as serial port pins
0 = Disables module

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **SPISIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when device enters Idle mode
0 = Continue module operation in Idle mode

bit 12-7 **Unimplemented:** Read as ‘0’

bit 6 **SPIROV:** Receive Overflow Flag bit
1 = A new byte/word is completely received and discarded. The user software has not read the previous data in the SPIxBUF register
0 = No overflow has occurred

bit 5-2 **Unimplemented:** Read as ‘0’

bit 1 **SPITBF:** SPIx Transmit Buffer Full Status bit
1 = Transmit not yet started, SPIxTXB is full
0 = Transmit started, SPIxTXB is empty
Automatically set in hardware when CPU writes SPIxBUF location, loading SPIxTXB.
Automatically cleared in hardware when SPIx module transfers data from SPIxTXB to SPIxSR.

bit 0 **SPIRBF:** SPIx Receive Buffer Full Status bit
1 = Receive complete, SPIxRXB is full
0 = Receive is not complete, SPIxRXB is empty
Automatically set in hardware when SPIx transfers data from SPIxSR to SPIxRXB.
Automatically cleared in hardware when core reads SPIxBUF location, reading SPIxRXB.

17.0 INTER-INTEGRATED CIRCUIT™ (I^2C™)

> **Note:** This data sheet summarizes the features of the PIC24HJXXXGPX06/X08/X10 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"PIC24H Family Reference Manual"*, **Section 19. "Inter-Integrated Circuit™ (I^2C™)"** (DS70235), which is available from the Microchip website (www.microchip.com).

The Inter-Integrated Circuit (I^2C) module provides complete hardware support for both Slave and Multi-Master modes of the I^2C serial communication standard, with a 16-bit interface.

The PIC24HJXXXGPX06/X08/X10 devices have up to two I^2C interface modules, denoted as I2C1 and I2C2. Each I^2C module has a 2-pin interface: the SCLx pin is clock and the SDAx pin is data.

Each I^2C module 'x' (x = 1 or 2) offers the following key features:

- I^2C interface supporting both master and slave operation.
- I^2C Slave mode supports 7 and 10-bit address.
- I^2C Master mode supports 7 and 10-bit address.
- I^2C Port allows bidirectional transfers between master and slaves.
- Serial clock synchronization for I^2C port can be used as a handshake mechanism to suspend and resume serial transfer (SCLREL control).
- I^2C supports multi-master operation; detects bus collision and will arbitrate accordingly.

17.1 Operating Modes

The hardware fully implements all the master and slave functions of the I^2C Standard and Fast mode specifications, as well as 7 and 10-bit addressing.

The I^2C module can operate either as a slave or a master on an I^2C bus.

The following types of I^2C operation are supported:

- I^2C slave operation with 7-bit address
- I^2C slave operation with 10-bit address
- I^2C master operation with 7 or 10-bit address

For details about the communication sequence in each of these modes, please refer to the *"PIC24H Family Reference Manual"*.

17.2 I^2C Registers

I2CxCON and I2CxSTAT are control and status registers, respectively. The I2CxCON register is readable and writable. The lower six bits of I2CxSTAT are read-only. The remaining bits of the I2CSTAT are read/write.

I2CxRSR is the shift register used for shifting data, whereas I2CxRCV is the buffer register to which data bytes are written, or from which data bytes are read. I2CxRCV is the receive buffer. I2CxTRN is the transmit register to which bytes are written during a transmit operation.

The I2CxADD register holds the slave address. A status bit, ADD10, indicates 10-bit Address mode. The I2CxBRG acts as the Baud Rate Generator (BRG) reload value.

In receive operations, I2CxRSR and I2CxRCV together form a double-buffered receiver. When I2CxRSR receives a complete byte, it is transferred to I2CxRCV and an interrupt pulse is generated.

REGISTER 18-2: UxSTA: UARTx STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	R/W-0 HC	R/W-0	R-0	R-1
UTXISEL1	UTXINV	UTXISEL0	—	UTXBRK	UTXEN[(1)]	UTXBF	TRMT
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R-1	R-0	R-0	R/C-0	R-0
URXISEL<1:0>		ADDEN	RIDLE	PERR	FERR	OERR	URXDA
bit 7							bit 0

Legend:	HC = Hardware cleared	C = Clear only bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15,13 **UTXISEL<1:0>:** Transmission Interrupt Mode Selection bits
`11` = Reserved; do not use
`10` = Interrupt when a character is transferred to the Transmit Shift Register, and as a result, the transmit buffer becomes empty
`01` = Interrupt when the last character is shifted out of the Transmit Shift Register; all transmit operations are completed
`00` = Interrupt when a character is transferred to the Transmit Shift Register (this implies there is at least one character open in the transmit buffer)

bit 14 **UTXINV:** Transmit Polarity Inversion bit
If IREN = `0`:
`1` = UxTX Idle state is ‘`0`’
`0` = UxTX Idle state is ‘`1`’
If IREN = `1`:
`1` = IrDA® encoded UxTX Idle state is ‘`1`’
`0` = IrDA® encoded UxTX Idle state is ‘`0`’

bit 12 **Unimplemented:** Read as ‘`0`’

bit 11 **UTXBRK:** Transmit Break bit
`1` = Send Sync Break on next transmission – Start bit, followed by twelve ‘`0`’ bits, followed by Stop bit; cleared by hardware upon completion
`0` = Sync Break transmission disabled or completed

bit 10 **UTXEN:** Transmit Enable bit[(1)]
`1` = Transmit enabled, UxTX pin controlled by UARTx
`0` = Transmit disabled, any pending transmission is aborted and buffer is reset. UxTX pin controlled by port.

bit 9 **UTXBF:** Transmit Buffer Full Status bit (read-only)
`1` = Transmit buffer is full
`0` = Transmit buffer is not full, at least one more character can be written

bit 8 **TRMT:** Transmit Shift Register Empty bit (read-only)
`1` = Transmit Shift Register is empty and transmit buffer is empty (the last transmission has completed)
`0` = Transmit Shift Register is not empty, a transmission is in progress or queued

bit 7-6 **URXISEL<1:0>:** Receive Interrupt Mode Selection bits
`11` = Interrupt is set on UxRSR transfer making the receive buffer full (i.e., has 4 data characters)
`10` = Interrupt is set on UxRSR transfer making the receive buffer 3/4 full (i.e., has 3 data characters)
`0x` = Interrupt is set when any character is received and transferred from the UxRSR to the receive buffer. Receive buffer has one or more characters.

Note 1: Refer to **Section 17. “UART”** (DS70232) in the *“PIC24H Family Reference Manual”* for information on enabling the UART module for transmit operation.

REGISTER 19-20: CiRXMnSID: ECAN™ MODULE ACCEPTANCE FILTER MASK n STANDARD IDENTIFIER

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID10	SID9	SID8	SID7	SID6	SID5	SID4	SID3
bit 15							bit 8

R/W-x	R/W-x	R/W-x	U-0	R/W-x	U-0	R/W-x	R/W-x
SID2	SID1	SID0	—	MIDE	—	EID17	EID16
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-5 **SID<10:0>:** Standard Identifier bits
1 = Include bit SIDx in filter comparison
0 = Bit SIDx is don’t care in filter comparison

bit 4 **Unimplemented:** Read as ‘0’

bit 3 **MIDE:** Identifier Receive Mode bit
1 = Match only message types (standard or extended address) that correspond to EXIDE bit in filter
0 = Match either standard or extended address message if filters match
(i.e., if (Filter SID) = (Message SID) or if (Filter SID/EID) = (Message SID/EID))

bit 2 **Unimplemented:** Read as ‘0’

bit 1-0 **EID<17:16>:** Extended Identifier bits
1 = Include bit EIDx in filter comparison
0 = Bit EIDx is don’t care in filter comparison

REGISTER 19-21: CiRXMnEID: ECAN™ TECHNOLOGY ACCEPTANCE FILTER MASK n EXTENDED IDENTIFIER

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID15	EID14	EID13	EID12	EID11	EID10	EID9	EID8
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID7	EID6	EID5	EID4	EID3	EID2	EID1	EID0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **EID<15:0>:** Extended Identifier bits
1 = Include bit EIDx in filter comparison
0 = Bit EIDx is don’t care in filter comparison

REGISTER 20-1: ADxCON1: ADCx CONTROL REGISTER 1 (where x = 1 or 2) (CONTINUED)

bit 3 **SIMSAM:** Simultaneous Sample Select bit (only applicable when CHPS<1:0> = 01 or 1x)

When AD12B = 1, SIMSAM is: U-0, Unimplemented, Read as '0'

1 = Samples CH0, CH1, CH2, CH3 simultaneously (when CHPS<1:0> = 1x); or
Samples CH0 and CH1 simultaneously (when CHPS<1:0> = 01)

0 = Samples multiple channels individually in sequence

bit 2 **ASAM:** ADC Sample Auto-Start bit

1 = Sampling begins immediately after last conversion. SAMP bit is auto-set

0 = Sampling begins when SAMP bit is set

bit 1 **SAMP:** ADC Sample Enable bit

1 = ADC sample/hold amplifiers are sampling

0 = ADC sample/hold amplifiers are holding

If ASAM = 0, software may write '1' to begin sampling. Automatically set by hardware if ASAM = 1.
If SSRC = 000, software may write '0' to end sampling and start conversion. If SSRC ≠ 000, automatically cleared by hardware to end sampling and start conversion.

bit 0 **DONE:** ADC Conversion Status bit

1 = ADC conversion cycle is completed.

0 = ADC conversion not started or in progress

Automatically set by hardware when analog-to-digital conversion is complete. Software may write '0' to clear DONE status (software not allowed to write '1'). Clearing this bit will NOT affect any operation in progress. Automatically cleared by hardware at start of a new conversion.

24.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of PIC24HJXXXGPX06/X08/X10 electrical characteristics. Additional information is provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the PIC24HJXXXGPX06/X08/X10 family are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings(1)

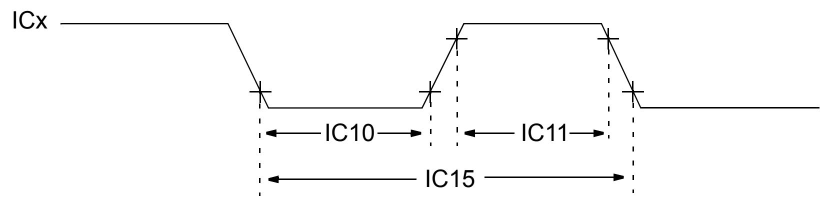
Ambient temperature under bias .... -40°C to +85°C
Storage temperature .... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} .... -0.3V to +4.0V
Voltage on any combined analog and digital pin and $\overline{MCLR}$, with respect to V_{SS} .... -0.3V to (V_{DD} + 0.3V)
Voltage on any digital-only pin with respect to V_{SS} .... -0.3V to +5.6V
Voltage on V_{CAP}/V_{DDCORE} with respect to V_{SS} .... 2.25V to 2.75V
Maximum current out of V_{SS} pin .... 300 mA
Maximum current into V_{DD} pin(2) .... 250 mA
Maximum output current sunk by any I/O pin(3) .... 4 mA
Maximum output current sourced by any I/O pin(3) .... 4 mA
Maximum current sunk by all ports .... 200 mA
Maximum current sourced by all ports(2) .... 200 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 24-2).

3: Exceptions are CLKOUT, which is able to sink/source 25 mA, and the $V_{REF}+$, $V_{REF}-$, SCLx, SDAx, PGECx and PGEDx pins, which are able to sink/source 12 mA.

FIGURE 24-6: INPUT CAPTURE (CAPx) TIMING CHARACTERISTICS



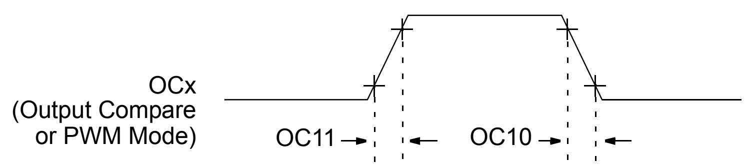
Note: Refer to Figure 24-1 for load conditions.

TABLE 24-25: INPUT CAPTURE TIMING REQUIREMENTS

AC CHARACTERISTICS				**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial			
Param No.	**Symbol**	**Characteristic[(1)]**		**Min**	**Max**	**Units**	**Conditions**
IC10	TccL	ICx Input Low Time	No Prescaler	0.5 TCY + 20	—	ns	—
			With Prescaler	10	—	ns	
IC11	TccH	ICx Input High Time	No Prescaler	0.5 TCY + 20	—	ns	—
			With Prescaler	10	—	ns	
IC15	TccP	ICx Input Period		(TCY + 40)/N	—	ns	N = prescale value (1, 4, 16)

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 24-7: OUTPUT COMPARE MODULE (OCx) TIMING CHARACTERISTICS



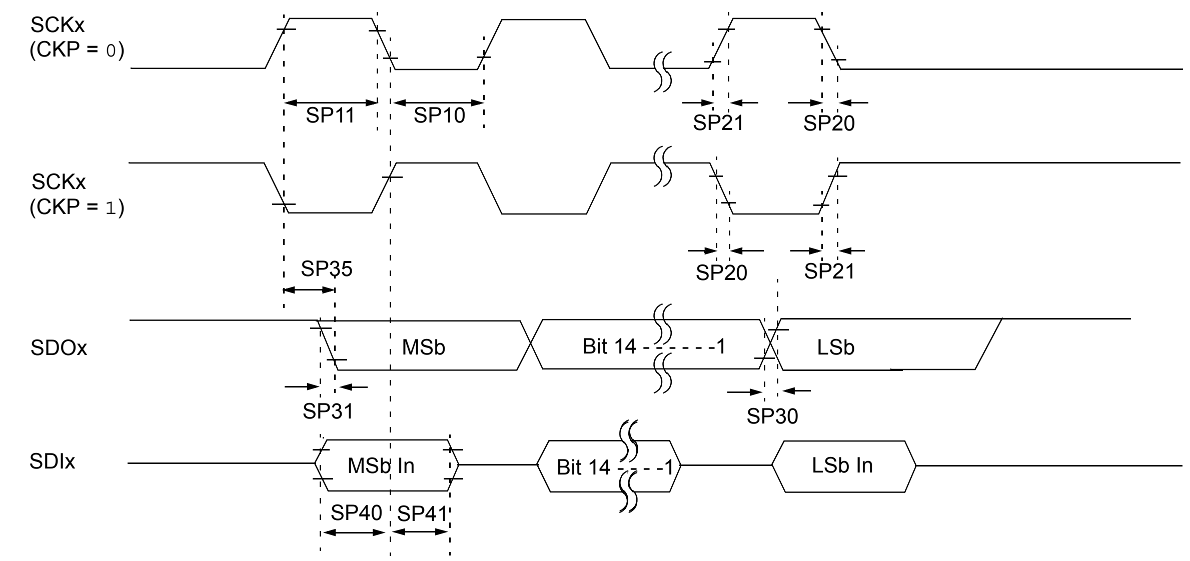
Note: Refer to Figure 24-1 for load conditions.

TABLE 24-26: OUTPUT COMPARE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param No.	**Symbol**	**Characteristic[(1)]**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See parameter D032
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See parameter D031

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 24-9: SPIx MODULE MASTER MODE (CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 24-1 for load conditions.

TABLE 24-28: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP10	TscL	SCKx Output Low Time	TCY/2	—	—	ns	See **Note 3**
SP11	TscH	SCKx Output High Time	TCY/2	—	—	ns	See **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See parameter D032 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See parameter D031 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See parameter D032 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See parameter D031 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	23	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—

Note 1: These parameters are characterized but not tested in manufacturing.
2: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.
3: The minimum clock period for SCKx is 100 ns. Therefore, the clock generated in Master mode must not violate this specification.
4: Assumes 50 pF load on all SPIx pins.

I

J

M

N

O

P

R

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PIC 24 HJ 256 GP6 10 T I/PT - XXX

- **Microchip Trademark** — PIC
- **Architecture** — 24
- **Flash Memory Family** — HJ
- **Program Memory Size (KB)** — 256
- **Product Group** — GP6
- **Pin Count** — 10
- **Tape and Reel Flag (if applicable)** — T
- **Temperature Range** — I
- **Package** — PT
- **Pattern** — XXX

Architecture:	24	=	16-bit Microcontroller
Flash Memory Family:	HJ	=	Flash program memory, 3.3V, High-speed
Product Group:	GP2	=	General purpose family
	GP3	=	General purpose family
	GP5	=	General purpose family
	GP6	=	General purpose family
Pin Count:	06	=	64-pin
	10	=	100-pin
Temperature Range:	I	=	-40°C to +85°C (Industrial)
Package:	PT	=	10x10 or 12x12 mm TQFP (Thin Quad Flatpack)
	PF	=	14x14 mm TQFP (Thin Quad Flatpack)
Pattern:	Three-digit QTP, SQTP, Code or Special Requirements (blank otherwise)		
	ES	=	Engineering Sample

Examples:

a) PIC24HJ256GP210I/PT:
General-purpose PIC24H, 256 KB program memory, 100-pin, Industrial temp., TQFP package.

b) PIC24HJ64GP506I/PT-ES:
General-purpose PIC24H, 64 KB program memory, 64-pin, Industrial temp., TQFP package, Engineering Sample.